

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	2 X 2 X 0.55 (1.0 X 1.6 EP)
Lead Count	6
Terminal Finish	NiPdAu
MS Number	MS010676C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.00E-03	83.25	832500	34.28	342767
Thermosets	Epoxy resin	158117-90-9 / 85954-11-6	3.25E-04	5.42	54200	2.23	22316
Thermosets	Phenol resin	26834-02-6	2.07E-04	3.45	34500	1.42	14205
Other inorganic materials	Metal Hydroxide	1309-42-8 / 20427-58-1	3.25E-04	5.42	54200	2.23	22316
Others	Others	Proprietary	1.48E-04	2.46	24600	1.01	10129
Subtotal			6.00E-03	100.00	1000000	41.17	411733

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.25 E-03	96.20	962000	36.04	360433
Copper & its alloys	Nickel	7440-02-0	1.64 E-04	3.00	30000	1.12	11240
Copper & its alloys	Silicon	7440-21-3	3.55 E-05	0.65	6500	0.24	2435
Copper & its alloys	Magnesium	7439-95-4	8.19 E-06	0.15	1500	0.06	562
Subtotal			5.46 E-03	100.00	1000000	37.47	374671

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.97 E-04	95.02	950185	2.04	20401
Precious metals	Palladium	7440-05-3	1.27 E-05	4.06	40590	0.09	872
Precious metals	Gold	7440-57-5	2.89 E-06	0.92	9225	0.020	198
Subtotal			3.13 E-04	100.00	1000000	2.15	21471

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.75 E-05	100.0	1000000	0.46	4633

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.63 E-03	100.0	1000000	18.01	180133

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.26 E-05	77.00	770000	0.57	5667
Other organic materials	Acrylic resin	Proprietary	7.51 E-06	7.00	70000	0.05	515
Other organic materials	Acrylate	Proprietary	5.90 E-06	5.50	55000	0.04	405
Other organic materials	Polybutadiene derivative	Proprietary	4.83 E-06	4.50	45000	0.03	331
Thermoset	Epoxy resin	Proprietary	2.68 E-06	2.50	25000	0.02	184
Other organic materials	Butadiene Copolymer	Proprietary	1.61 E-06	1.50	15000	0.01	110
Others	Additive	Proprietary	1.61 E-06	1.50	15000	0.01	110
Others	Peroxide	Proprietary	5.36 E-07	0.50	5000	0.004	37
Subtotal			1.07 E-04	100.0	1000000	0.74	7360

Package Totals			Weight (g) 1.46 E-02			Percentage (%) 100.00	PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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